## Substitute form 1449A/PTO INFORMATION DISCLOS STATEMENT BY APPLICANT (use as many sheets as necessary)

1B

Sheet

Examiner

Initials\*

Cite

No. 6.

2004.

1B

C	complete if Known
Application Number	10/780,529
Filing Date	February 17, 2004
First Named Inventor	Jong-Rong Jan et al;
Group Art Unit	2812
Confirmation No.:	1502
Attorney Docket Number	9180-30

			<u> </u>	S. PATENTS	AND PATENT PUBLICATIONS		
Examiner Initials*	Cite No	). 	U.S. Patent D	Kind Code	Name of Patentee or Applicant of Cited Document	Date of Publication Document MM-DD-YYY	
				(if known)		101101-00-1111	T
CAL		1. 5,	329,068		Hirata et al.	07/12/1994	
CAL			003/0027379A1		Liu	02/06/2003	
(AL	3	3. 20	003/0186487A1		Hogerl	10/02/2003	
	<u> </u>						
	$\vdash$	$\rightarrow$		<del> </del>			
	ļ			<del></del>			
	1	+		<del>                                     </del>			
•	<del>                                     </del>						
<u> </u>	<u>†                                      </u>	+					<del></del>
				·			
	<del> </del>	_		<b>_</b>		-	
		+					
	<del> </del>			<del> </del>		_	
	1 02				PATENT DOCUMENTS	-	
Examiner Initials*	Cite No.			Name of Patentee or Applicant of Cited  Document	Date of Publication of Cited Document	Т	
		Office	Number	Kind Code (if known)		MM-DD-YYYY	
AL	4.	EPO	0907207A2		NEC Corporation	04/07/1999	
cor	5.	wo	97/45871		ELCOTEQ NETWORK OY	12/04/1997	
	<del> </del>			<del></del>			
	-						
		_				<del></del>	<del></del>
			1				

	<b>//</b>		
Examiner Signature		Date Considered	7/25/05

OTHER NON PATENT LITERATURE DOCUMENTS

Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published

International Search Report for PCT/US2004/005818; Date of Mailing - September 28,

Substitute form 1449A/PTO Complete if Known **Application Number** not yet assigned INFORMATION DISCLOSURE Filing Date concurrently herewith First Named Inventor STATEMENT BY APPLICANT Jong-Rong Jan et al; Group Art Unit not yet assigned **Examiner Name** not yet assigned (use as many sheets as necessary) Sheet **Attorney Docket Number** 9180-30

			U.S. PATENTS	AND PATENT PUBLICATIONS		
Examiner	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited	Date of Publication of Cited	
Initials*		Number	Kind Code (if known)	Document	Document MM-DD-YYYY	
OPL	1.	US-3,625,837		Nelson et al;	12/07/1971	
i	2.	US-5,130,275		Dion	07/14/1992	
	3.	US-5,211,807		Yee	05/18/1993	
	4.	US-5,462,638		Datta et al;	10/31/1995	
	5.	US-5,470,787		Greer	11/28/1995	
	6.	US-5,471,092		Chan et al;	11/28/1995	
	7.	US-5,759,437		Datta et al;	06/02/1998	
	8.	US-5,796,168		Datta et al;	08/18/1998	
	9.	US-5,937,320		Andricacos et al;	08/10/1999	
- 1/	10.	US-6,015,505		David et al;	01/18/2000	
·V	11.	US-6,130,170		David et al;	10/10/2000	
CAPC	12.	US-6,332,988		Berger, Jr. et al;	12/25/2001	
		US-				
		<b>US</b>				
		US-				
	<u> </u>	US-				
		US-				
	-	US-				

				FOREIGN PA	ATENT DOCUMENTS		
Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited  Document	Date of Publication	T
		Office	Number	Kind Code (if known)		of Cited Document MM-DD-YYYY	
		<u> </u>					
		L					
<u> </u>		ļl					
		II					
		r	OTH	R NON PATEN	LITERATURE DOCUMENTS		
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published					
CAL	13.	R.B. Danzl and Allen McLaurin; "The Use of Concentrated Hydrogen Peroxide for the Removal of a TIW ARC from Aluminum Bond Pads" IEEE/CPMT Int'l Electronics Manufacturing Technology Symposium (1997) pp 99-104.					.,
CAL	14.	Akira Furuya and Yoshio Ohshita; "Ti concentration effect on adhesive energy at Cu/TiW interface";  Journal of Applied Physics, Vol. 84, No. 9, (Nov 1998) pp 4941-4944.					
CAL	15.	Julia H	awley and Van-Vo	; "Solutions to C	atastrophic Yield Problems in MCM-D Inte e on Multichip Modules and High Density	rconnect Packaging; pp 118-	
		1	<u> </u>				
		1				<del></del>	

	 	<i>!_</i>		1	,
Examiner Signature	<b>\</b>		Date Considered	7/25/	05

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.